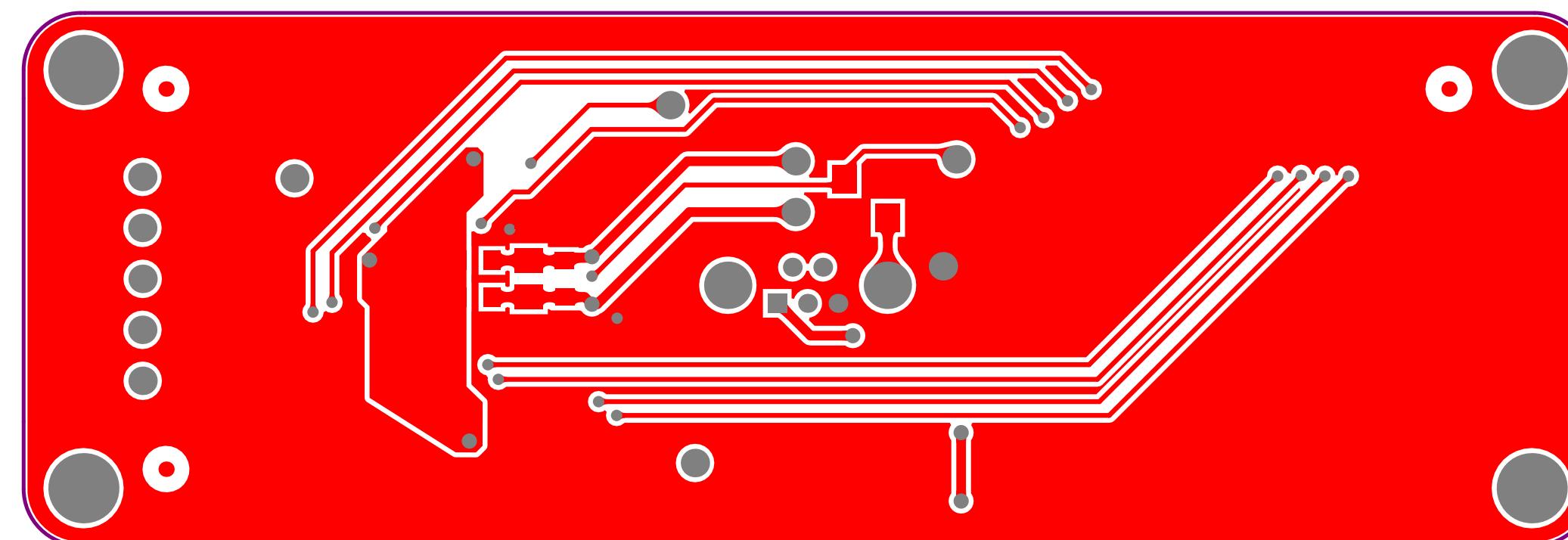
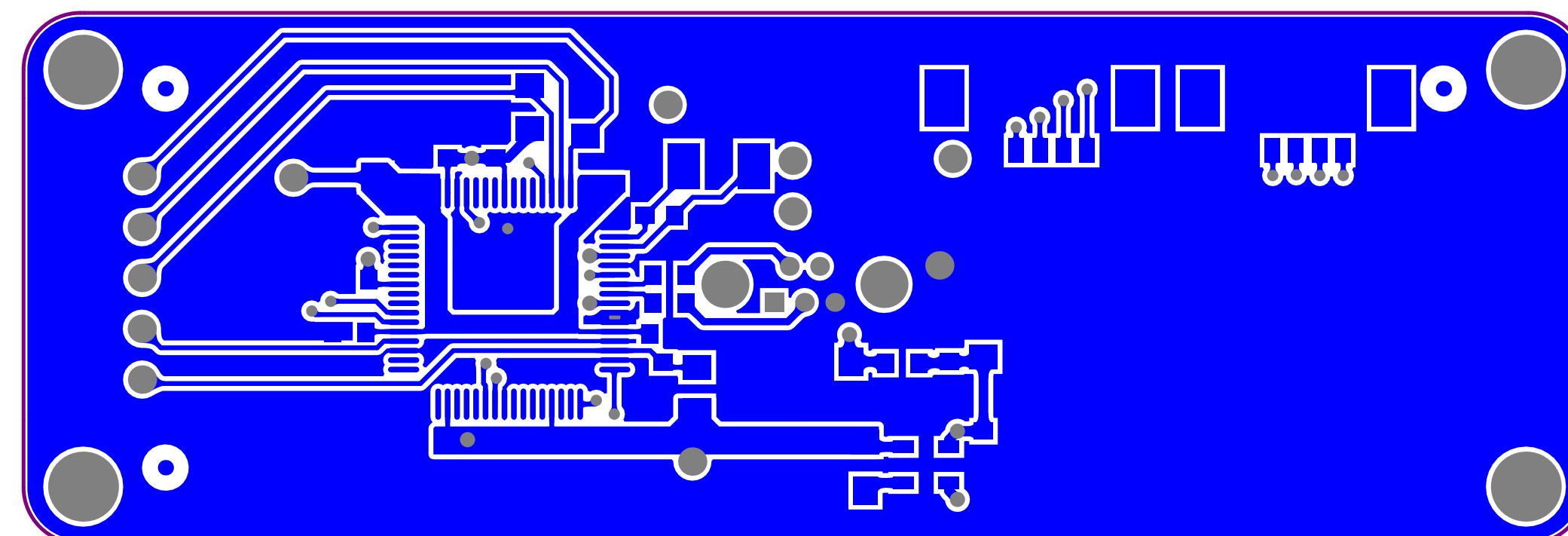


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.8	
1	Top Layer	Copper	1.40mil		
	Dielectric 1	FR-4	59.06mil	4.5	
2	Bottom Layer	Copper	1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.8	
	Bottom Overlay				



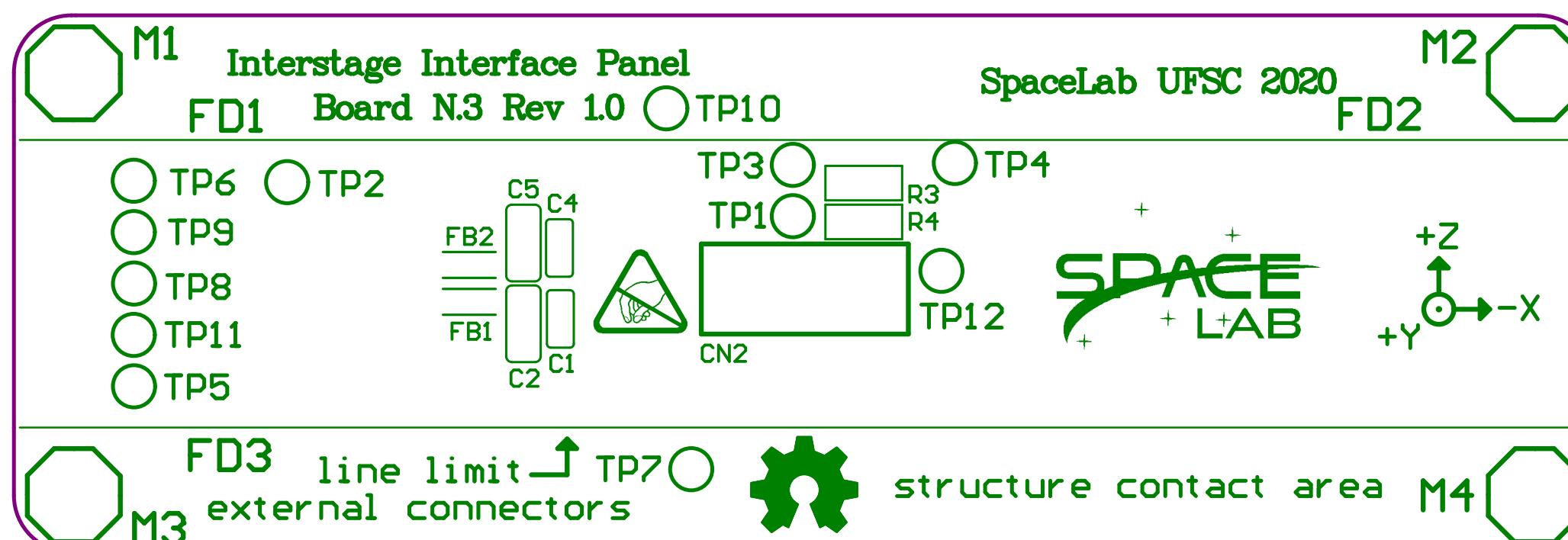
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MATERIAL: FR4		Silkscreen color: white	Project: IIP
Board Thickness: 1.6mm		Layers: 02	Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC
PCB Surface: HASL		Drawing: Yan C. de Azeredo	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.8	
1	Top Layer	Copper	1.40mil		
	Dielectric 1	FR-4	59.06mil	4.5	
2	Bottom Layer	Copper	1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.8	
	Bottom Overlay				



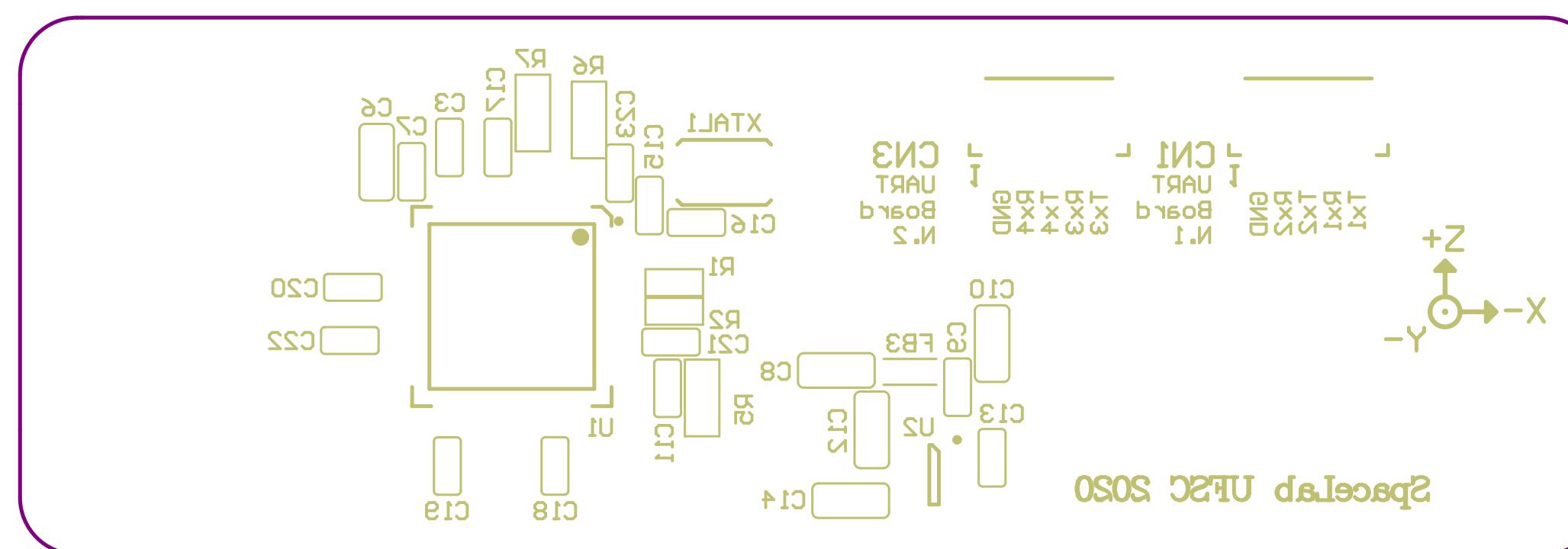
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MATERIAL: FR4		Silkscreen color: white	Project: IIP
Board Thickness: 1.6mm		Layers: 02	Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC
PCB Surface: HASL		Drawing: Yan C. de Azeredo	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.8	
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	Dielectric 1	FR-4	59.06mil	4.5	
2	Bottom Layer	Copper	1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.8	
	Bottom Overlay				



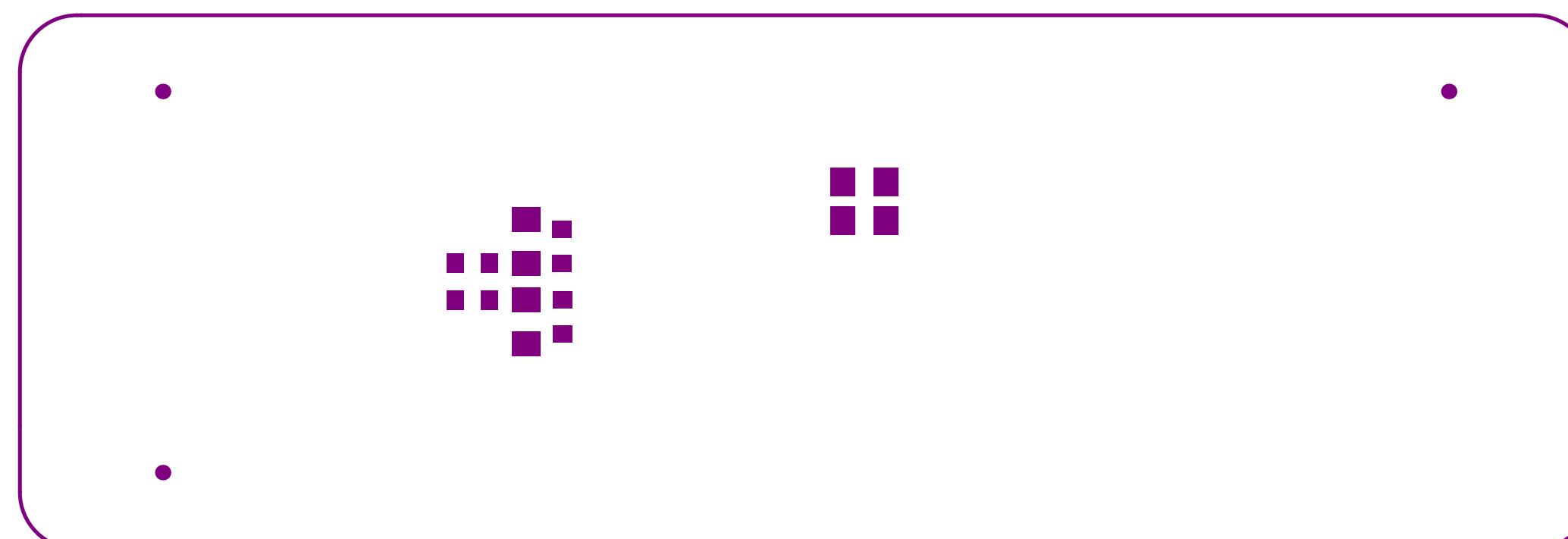
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MATERIAL: FR4	Silkscreen color: white	Project: IIP	
Board Thickness: 1.6mm	Layers: 02		Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC
PCB Surface: HASL	Drawing: Yan C. de Azeredo		

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.8	
1	Top Layer	Copper	1.40mil		
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2	Bottom Layer	Copper	1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.8	
	Bottom Overlay				



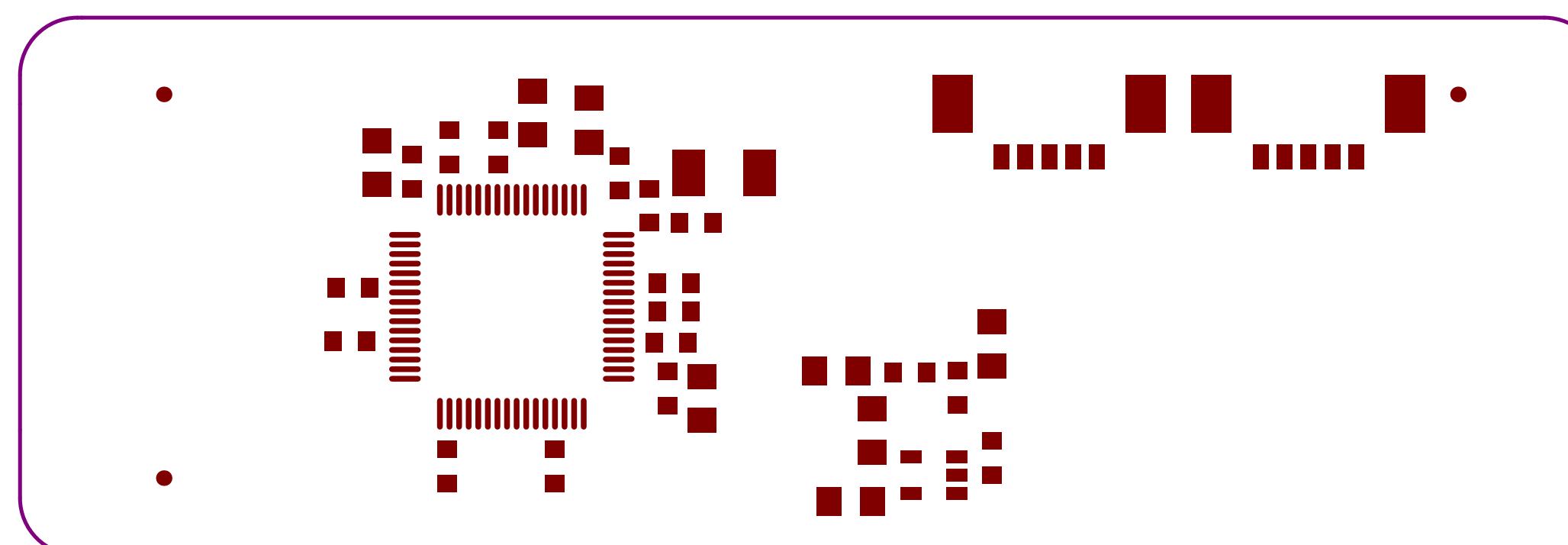
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MATERIAL: FR4		Silkscreen color: white	Project: IIP
Board Thickness: 1.6mm		Layers: 02	Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC
PCB Surface: HASL		Drawing: Yan C. de Azeredo	

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	Top Overlay				
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	Dielectric 1	FR-4	59.06mil	4.5	
2	Bottom Layer	Copper	1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.8	
	Bottom Overlay				



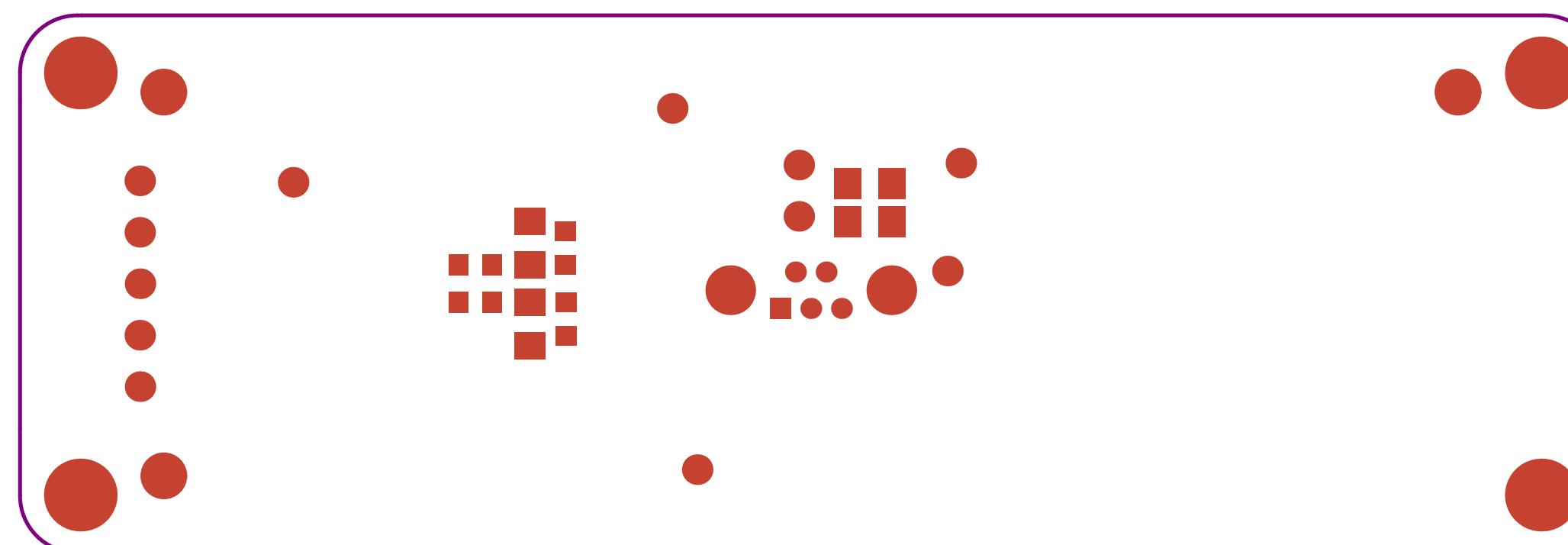
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Board Thickness: 1.6mm		Layers: 02	Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC
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	Bottom Solder	Solder Resist	0.40mil	3.8	
	Bottom Overlay				



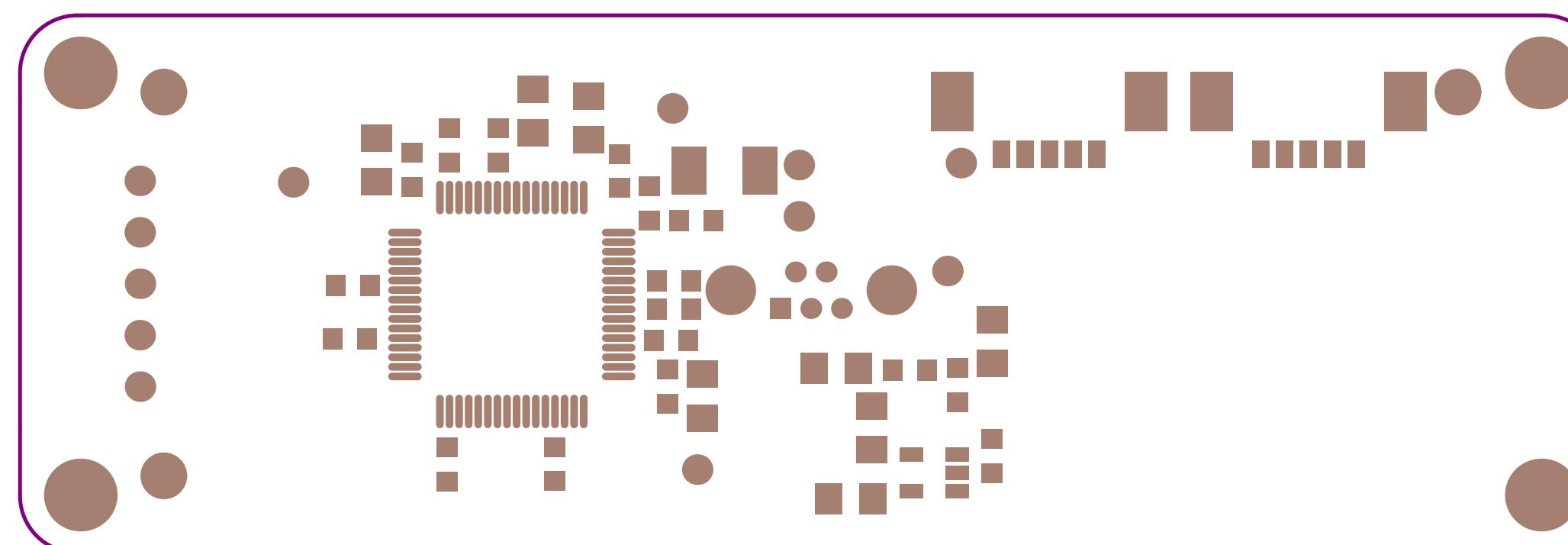
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MATERIAL: FR4		Silkscreen color: white	Project: IIP
Board Thickness: 1.6mm		Layers: 02	Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC
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	Bottom Solder	Solder Resist	0.40mil	3.8	
	Bottom Overlay				



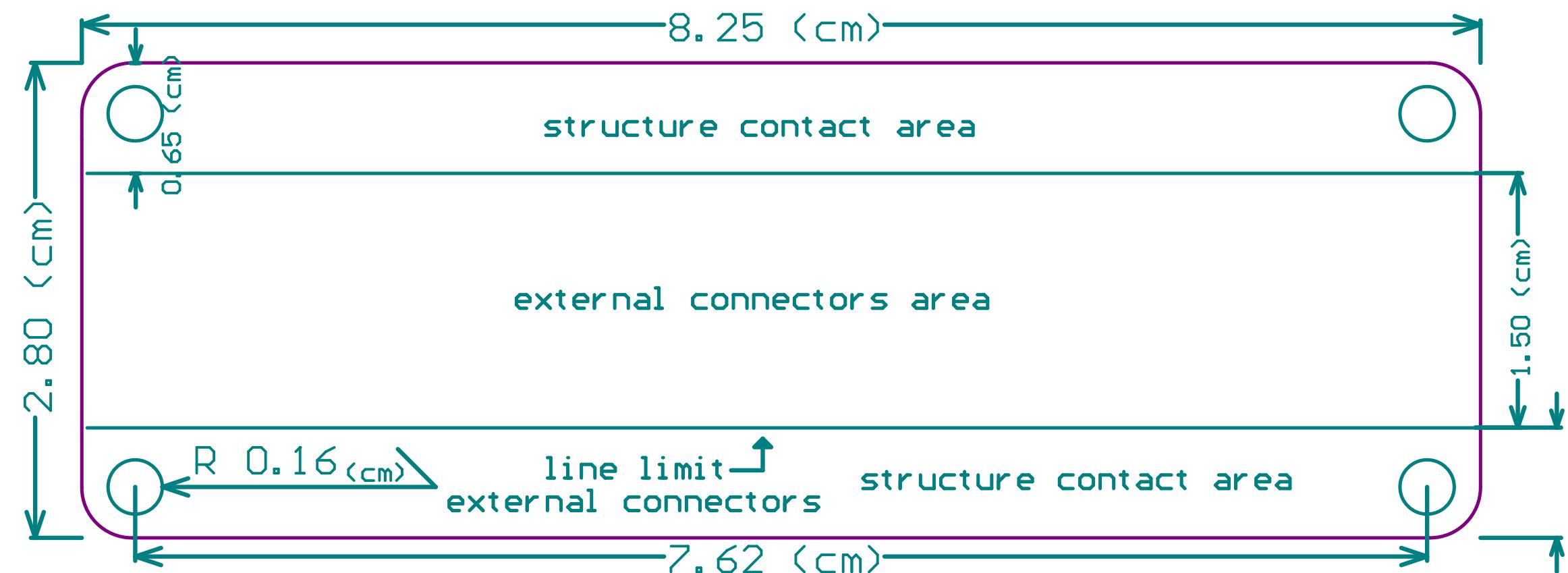
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MATERIAL: FR4		Silkscreen color: white	Project: IIP
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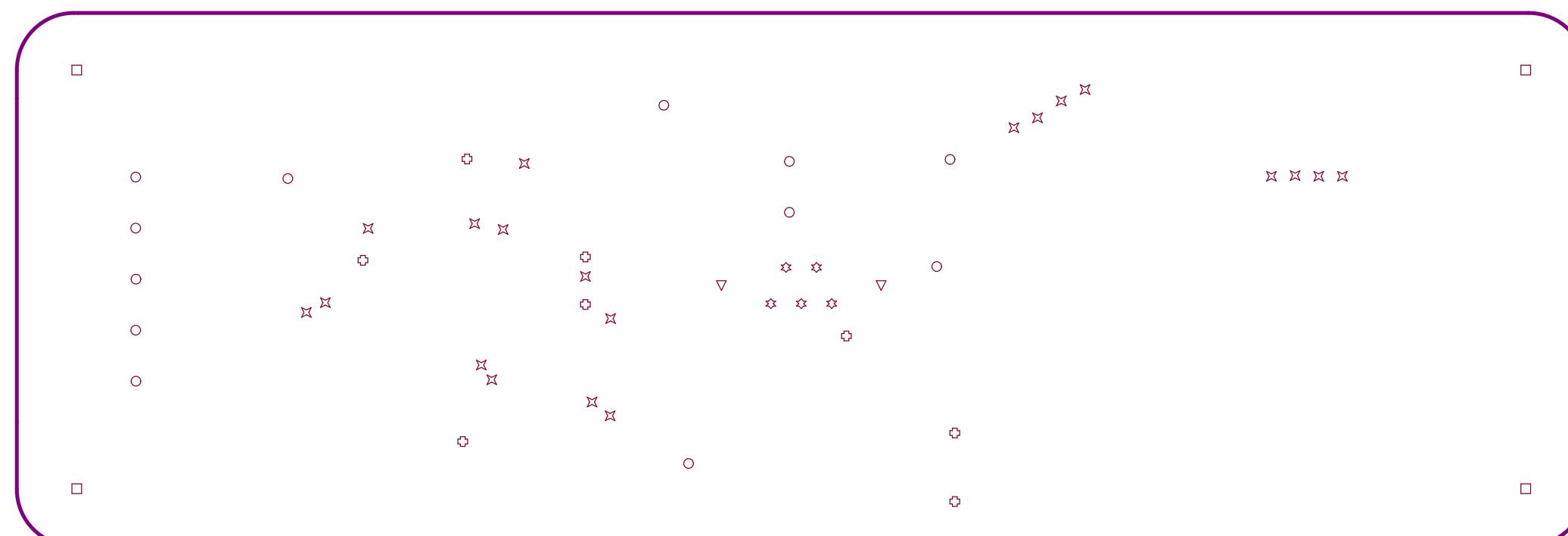
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.8	
1	Top Layer	Copper	1.40mil		
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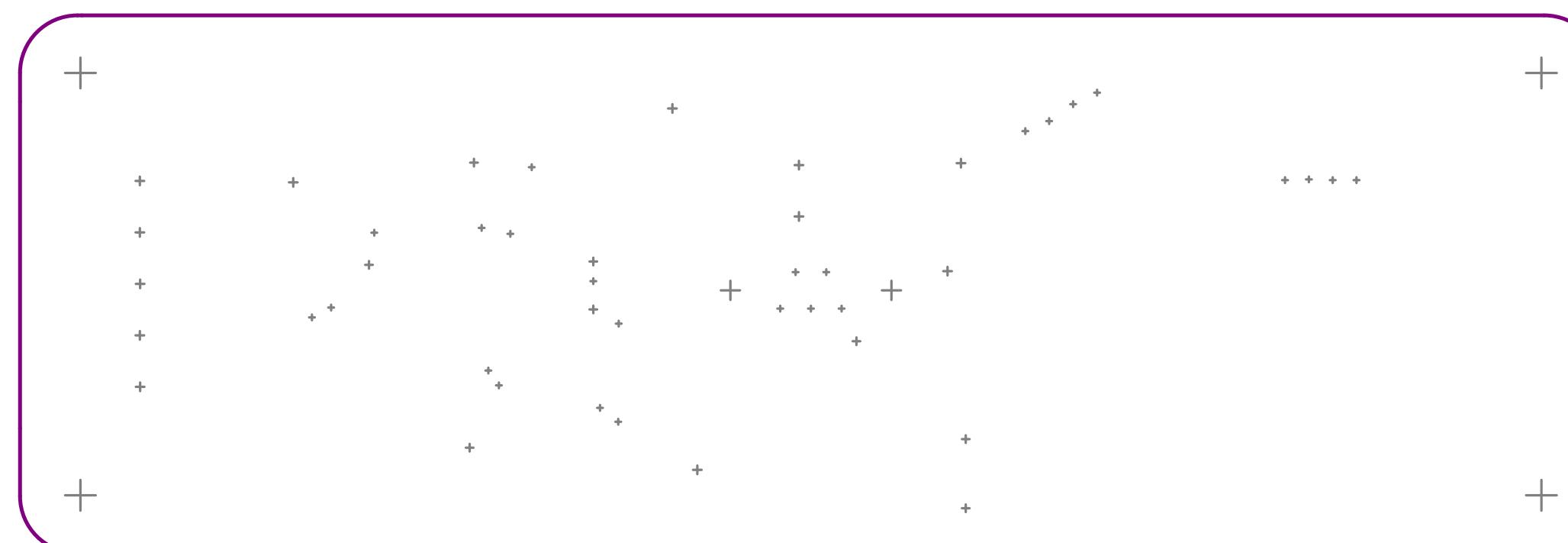
Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
☒	20	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v60h30m0mx0
✚	8	0.400mm (15.75mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v80h40m0mx0
❖	5	0.600mm (23.62mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
○	12	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c150h90
▽	2	2.000mm (78.74mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c250h200
□	4	3.200mm (125.98mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c370h320
51 Total								

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.8	
1	Top Layer	Copper	1.40mil		
	Dielectric 1	FR-4	59.06mil	4.5	
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	Bottom Solder	Solder Resist	0.40mil	3.8	
	Bottom Overlay				



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